



<b>IN THE UNITED STATES PATENT AND TRADEMARK OFFICE</b>	Application Number	<b>09/996,802</b>
	Filing Date	<b>November 30, 2001</b>
	First Named Inventor	<b>SATO</b>
	Group Art Unit	<b>1712</b>
	Examiner Name	<b>Feely, Michael J.</b>
	Attorney Docket Number	<b>2922-172</b>
<b>Title: RESIN COMPOUND FOR FABRICATING INTERLAYER DIELECTRIC OF PRINTED WIRING BOARD, RESIN SHEET AND RESIN APPLIED-COPPER FOIL FOR FORMING INSULATING LAYER USING THE RESIN COMPOUND, AND COPPER-CLAD LAMINATE USING THEM</b>		

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**AMENDMENT AND REQUEST FOR RECONSIDERATION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**RECEIVED**  
**MAY 27 2003**  
**GROUP 1700**

Dear Sir:

In response to the Office Action dated February 21, 2003, please amend the above  
identified U.S. patent application as follows:

**IN THE CLAIMS:**

Please amend claims 1 - 8, and add new claims 13-21 as shown on the following pages.

Marked-up copies of the original text of the amended claims are attached to this  
amendment. Material inserted is indicated by underlining (insertion) and material deleted is  
indicated by bracketing ([deletion]).

05/22/2003 HGUTEM1 00000084 09996802

01 FC:1202  
02 FC:1201

18.00 OP  
168.00 OP